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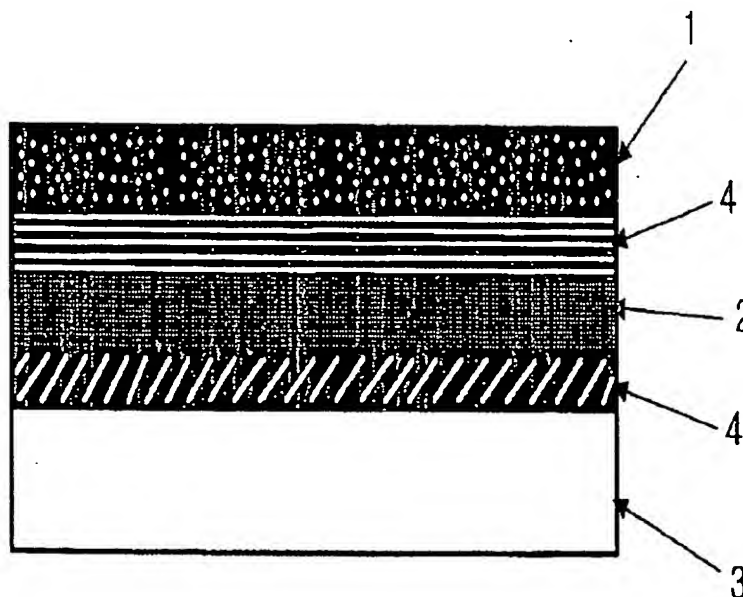
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(54) Title: BASE PAD POLISHING PAD AND MULTI-LAYER PAD COMPRISING THE SAME



(57) Abstract: Disclosed is a base pad of polishing pad, which is used in conjunction with polishing slurry during a chemical-mechanical polishing or planarizing process, and a multilayer pad using the same. Since the base pad according to the present invention does not have fine pores, it is possible to prevent premeation of polishing slurry and water and to avoid nonuniformity of physical properties. Therby, it is possible to lengthen the lifetime of the polishing pad.